

BSR92P-VB Datasheet P-Channel 200V (D-S)MOSFET

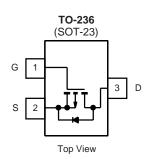
PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} ()	I _D (A)	Q _g (Typ.)		
- 200	0.8 at V _{GS} = - 10 V	- 0.80	8.0		
	0.9 at V _{GS} =- 6.0 V	- 0.70	0.0		

FEATURES

- Halogen-free According to IEC 61249-2-21
 Available
- Trench Power MOSFET
- Ultra Low On-Resistance
- Small Size

APPLICATIONS

Active Clamp Circuits in DC/DC Power Supplies



Parameter	Symbol	5 s	Steady State	Unit	
Drain-Source Voltage		V _{DS}	- 200		V
Gate-Source Voltage		V _{GS}	± 20		
Quality of the Armed (T Area 20) a h	T _A = 25 °C	I _D	- 0.80	- 0.64	
Continuous Drain Current (T _J = 150 °C) ^{a, b}	T _A = 70 °C		- 0.70	- 0.51	
Pulsed Drain Current		I _{DM}	- 2.5		А
Continuous Source Current (Diode Conduction) ^{a, b}		۱ _S	- 1.0	- 0.6	
Single Pulse Avalanche Current	L = 1.0 mH	I _{AS}	4.0		
Single Pulse Avalanche Energy	L = 1.0 mm	E _{AS}			mJ
	T _A = 25 °C	D	1.45	0.95	W
Maximum Power Dissipation ^{a, b}	T _A = 70 °C	P _D	0.8	0.48	
Operating Junction and Storage Temperature Ra	nge	T _J , T _{stg}	- 55	to 150	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum handlan ta Anthianta	t ≤ 5 s	R _{thJA}	75	100	
Maximum Junction-to-Ambient ^a	Steady State		120	166	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	40	50	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

b. Pulse width limited by maximum junction temperature.



			Limits				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 V, I_D = -250 \mu A$	- 200			V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 2.5		- 4.5	v	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$		- 1			
		V_{DS} = - 200 V, V_{GS} = 0 V, T_{J} = 55 °C			- 10	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS}\!\leq$ - 15 V, V_{GS} = 10 V	- 1.0			Α	
	R _{DS(on)}	$V_{GS} = -10 \text{ V}, \text{ I}_{D} = -0.5 \text{ A}$		0.80			
Drain-Source On-Resistance ^a		V_{GS} = - 6.0 V, I _D = - 0.5 A		0.90			
Forward Transconductance ^a	9 _{fs}	$V_{DS} = -15 \text{ V}, \text{ I}_{D} = -0.5 \text{ A}$		1.8		S	
Diode Forward Voltage	V _{SD}	I_{S} = - 1.0 A, V_{GS} = 0 V		- 0.85	- 1.2	V	
Dynamic ^b							
Total Gate Charge	Qg	<u> </u>		8.0	12		
Gate-Source Charge	Q _{gs}	V _{DS} = - 100 V, V _{GS} = 10 V In ≅ - 0.5 A		1.3		nC	
Gate-Drain Charge	Q _{gd}			2.5			
Gate Resistance	Rg	f = 1.0 MHz		8.0		^	
Input Capacitance	C _{iss}			370	510	pF	
Output Capacitance	C _{oss}	V_{DS} = - 25 V, V_{GS} = 0 V, f = 1 MHz		28			
Reverse Transfer Capacitance	C _{rss}			16			
Switching ^c							
Turn-On Time	t _{d(on)}	100 V D 100		8	12		
	tr	V _{DD} = - 100 V, R _L = 100 ∧ I _D ≅ - 1.0 A, V _{GEN} = - 10 V		11	17	ns	
Turn Off Time	t _{d(off)}	$R_a = 6 \land$		16	25		
Turn-Off Time	t _f	g		11	17		
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 0.5 A, dl/dt = 100 A/μs		140	200	nC	

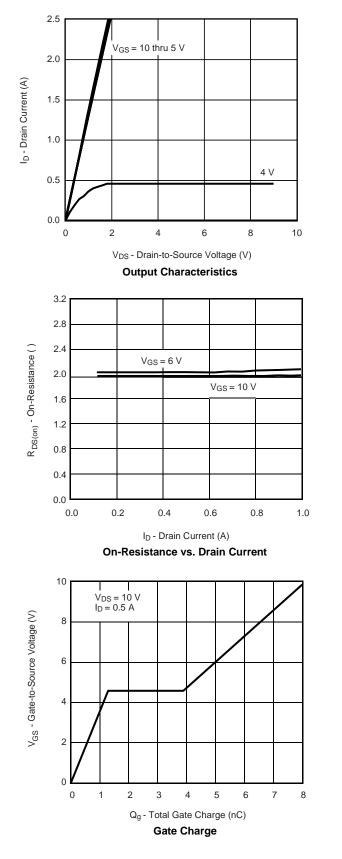
Notes:

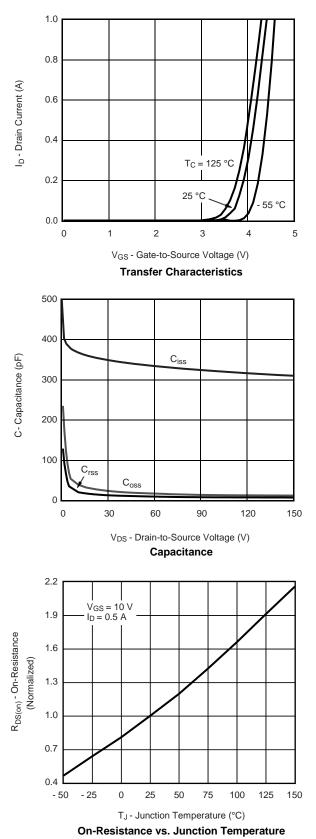
a. Pulse test: PW ≤ 300 µs duty cycle ≤ 2 %.
b. For DESIGN AID ONLY, not subject to production testing.
c. Switching time is essentially independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

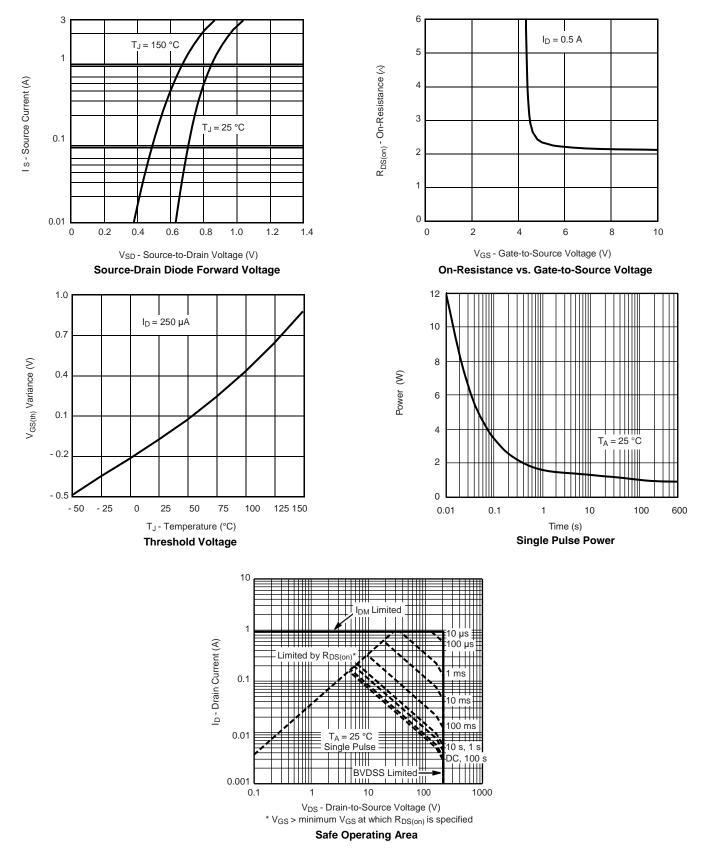


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





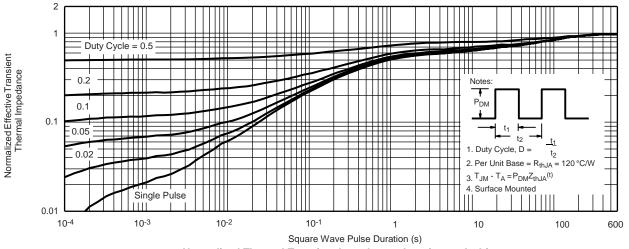




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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



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